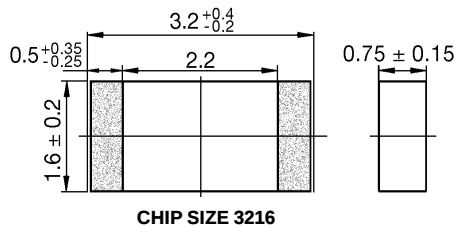
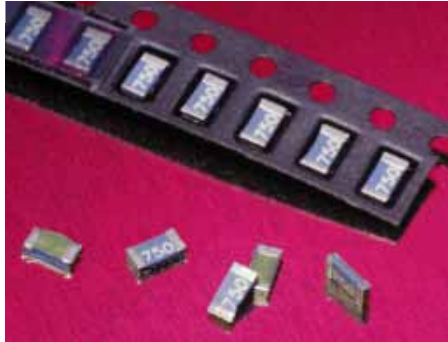
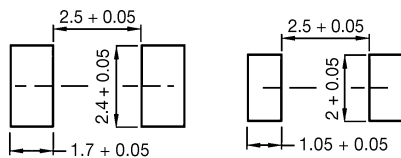


Chip Fuse
Fast-Acting**Solder Pad Layout:**

Wave

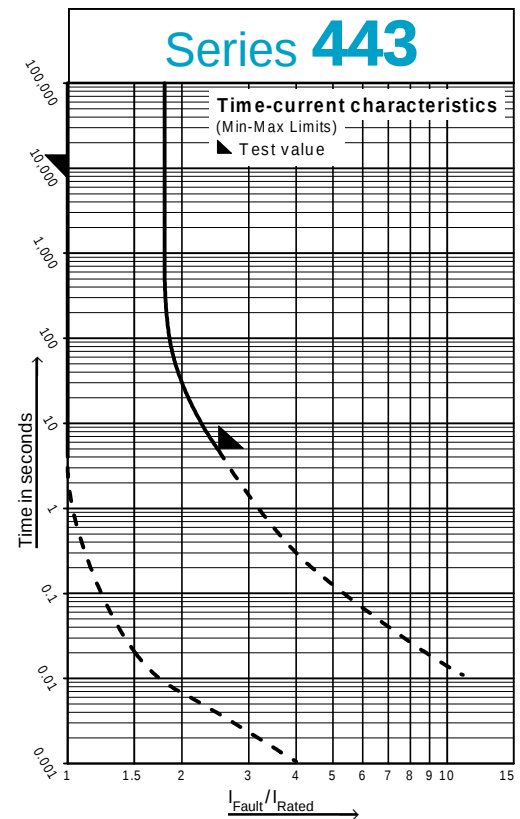
Reflow



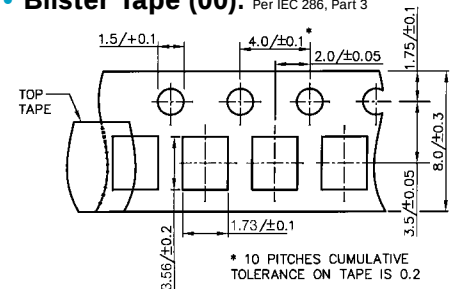
Copper layer thickness: 0.035mm

UL 248-14, 63V

- **FaxBack Document # 321:**
- **Approvals:**
cULus Recognized: File No. E 67006
- **Packaging:**
00: Blister Tape (3000 pcs. per Reel)
- **Soldering Conditions:**
235°C, 2 sec. (Wave and Reflow)
- **Soldering Heat Resistance:**
260°C, 10 sec. (IEC 68-2-58)
- **Recommended Solder Glue:**
Grace Amicon 125 F
- **Material:**
Housing:¹ Ceramic substrate,
Glass encapsulated
Terminals: Tinned, metallized
- **Vibration Resistance:**
24 cycles each 15 min. (EN 60068-6)
10 - 60Hz at 0.75mm amplitude
60 - 2000Hz at 10g acceleration

Series 443

Note: Contact WICKMANN for individual I-t curves

Blister Tape (00): Per IEC 286, Part 3**Limits for Pre-arcing Time**

Rated Current	100% 	250% 
750mA ... 2.00A	> 4h	< 5s

Permissible continuous operating current is $\leq 70\%$ at ambient temperature of 23°C (73.4°F).

Rated Current ² / Rated Voltage	Amp Code	Breaking Capacity	Voltage Drop (max) $100\% \times I_{Rated}$ (mV) 	Melting Integral (max) $1000\% \times I_{Rated}$ (A ² s) 	Approvals
750mA / 63V	0750	50A at 63VAC/DC (AC) $\cos \phi = 1.0$	600	0.03	• • • •
1.00A / •	1100		530	0.05	
1.50A / •	1150		450	0.2	
2.00A / •	1200		440	0.4	

¹ solder fuse with marked side facing up and avoid conducting paths below the fuse² for lower amp ratings, see Series 441**Order Information**

Qty.	Order-Number	Series	Amp Code	Packaging
		4 4 3		0 0 0